

Global Multilayer Printed-wiring Board Market Data Survey Report 2025

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Abstracts

Summary

Multilayer printed-wiring boards are made from the same base material with copper foil on the top & bottom and one or more “inner layer” cores. The number of “layers” corresponds to the number of copper foil layers.

The global Multilayer Printed-wiring Board market will reach xxx Million USD in 2017 with CAGR xx% from 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

Nippon Mektron

Zhen Ding Technology

Unimicron

Young Poong Group

Samsung Electro-Mechanics

Ibiden

Tripod

TTM Technologies

Sumitomo Electric SEI

Daeduck Group

Nanya PCB

Compeq

HannStar Board

LG Innotek

AT&S

Meiko

Chin-Poon

Shennan

WUS

Major applications as follows:

Consumer electronics

Communications

Computer related industry

Automotive industry

Others

Regional market size, production data and export & import:

Asia-Pacific

North America

Europe

South America

Middle East & Africa

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